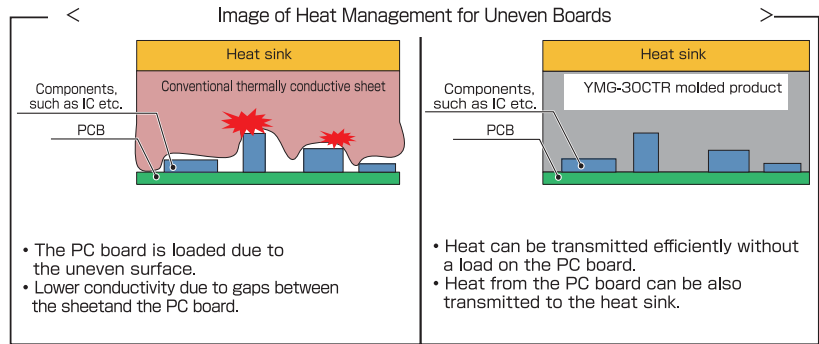


Injection-moldable, thermally conductive elastomer

3D molding

Three-dimensional shape enables heat management with low load for uneven component side of PC boards etc.

The product fits closely on boards to transmit the heat from both components such as ICs, and the board itself to heat sink etc.



Thermal conductivity properties

Vibration and thermal problems are managed simultaneously.

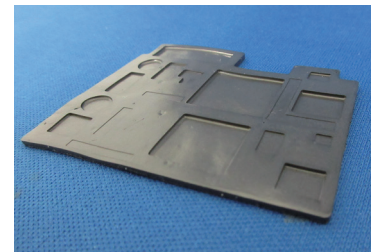
Non-Silicone material Solution for electric-contact failures caused by siloxane.

Silicone free KG-GEL is a solution for electric-contact failures caused by siloxane.

Specifications

Molded components

Required shaped components can be produced by injection molding. KGS offers total support system from design to prototype and mass production to meet your requirement.

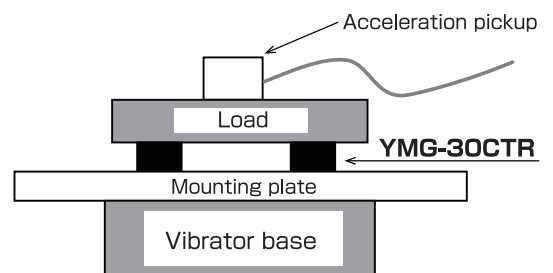


Properties

Item	Unit	Standard	YMG-3OCTR
Hardness	ASKER C	JIS K7312	30
Thermal Conductivity	W/m·K	ISO22007-2 (Hot Disc method)	1.0
Volume Resistivity	Ω·cm	JIS K6911	1.0×10 <sup>13</sup>
Specific Gravity	—	—	1.52
Recommended operation temperature	°C	—	-20~100
Resonance frequency*	Hz	—	257
Crossover frequency*	Hz	—	527
Loss factor*	—	—	0.78
Flame Retardancy	—	UL94	HB equivalent

\* Measured values according to the conditions on the right

< Test method >



< Testing conditions >

Sample : □5mm, t=1mm  
 Load : 400g  
 Support point number : Four point mounting